

## LISTING SHOWING THE AMENDMENT TO THE CLAIMS

This listing replaces all prior listings of claims.

### IN THE CLAIMS

Amend the claims as follows:

- 1 (Previously presented). A polymer mixture, the polymer mixture having semiconductive properties, the mixture comprising:
  - one or more semiconductive polymers; and
  - one or more non-semiconductive polymers.
- 2 (Previously presented). The polymer mixture as claimed in claim 1 wherein the semiconductive polymers include at least one of the group consisting of polythiophene, polyfluorene and/or polythienylenevinylene.
- 3 (Previously presented). The polymer mixture as claimed in claim 1 wherein the non-semiconductive polymers are selected from the group consisting of at least one of polystyrene, polymethyl methacrylate, cymel and/or poly isobutyl.
- 4 (Previously presented). The polymer mixture as claimed in claim 1 including solvents including at least one of chloroform, toluene, ketones, dioxane and/or heptane.
- 5 (Previously presented). The polymer mixture as claimed in claim 1 wherein it additionally contains molecules which are smaller than polymers, in particular oligomers, conductive molecules and/or semiconductive molecules.
- 6 (Previously presented). The polymer mixture as claimed in claim 1 wherein it

further includes of customary additives.

7 (Previously presented). The polymer mixture as claimed in claim 1 wherein it has a viscosity of more than 8 mpa.s.

8 (Previously presented). A printing process for the production of a semiconductive double layer by a known process, selected from the group consisting of at least one of screen printing, flexographic printing, offset printing, gravure printing and/or pad printing process, the polymer mixture as claimed in claim 1 being used as a print medium in the known process.

9 (Currently amended). A printing process for the production of a semiconductive double layer by a known process, selected from the group consisting of screen printing, flexographic printing, offset printing, gravure printing and/or pad printing process, the double layer produced by printing the a printing medium comprising the polymer mixture of claim 1 for forming containing

- the one or more semiconductive polymers in a first of ~~[[of]]~~ its layers, and
- the one or more non-semiconductive polymers in a second of its layers.

Claim 10, canceled.

11 (Previously presented). An electronic component which is produced using a polymer mixture as claimed in claim 1.

12 (Previously presented). An electronic component which is produced using a polymer mixture that forms a double layer as claimed in claim 9.

13. (Previously presented). An electronic component which is produced using a polymer mixture as claimed in claim 2.

14. (Previously presented). An electronic component which is produced using a polymer mixture as claimed in claim 3.

15 (Previously presented). An electronic component which is produced using a polymer mixture as claimed in claim 4.

16. (Previously presented). An electronic component which is produced using a polymer mixture as claimed in claim 5.

17. (Previously presented). An electronic component which is produced using a polymer mixture as claimed in claim 6.

18. (Previously presented). An electronic component which is produced using a polymer mixture as claimed in claim 7.

19 (Previously presented) The printing process for the production of a double layer as claimed in claim 9, in which a polymer mixture as claimed in claim 2 is used.

20 (Previously presented) The printing process for the production of a double layer as claimed in claim 9, in which a polymer mixture as claimed in claim 3 is used.